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環球晶圓股份有限公司

Global Family,
Global Solutions!



GlobalWafers (6488TT)
Q2 2026 Earnings Call

2026/08/04

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Executive Comment

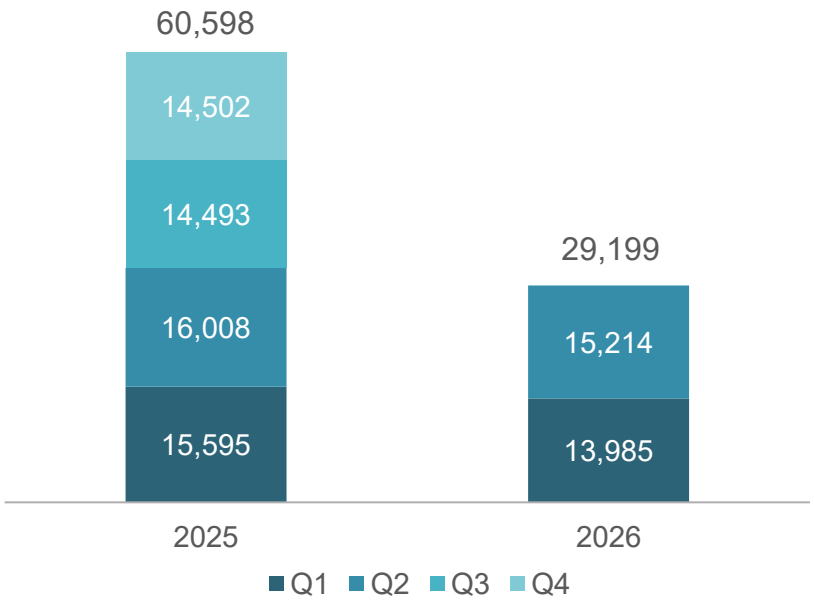
Executive Comments

➢ Financial Highlights

Revenue

- Q226 → NT$15.2 billion, 8.79% QoQ
- 1H26 → NT$29.2 billion, -7.60% YoY

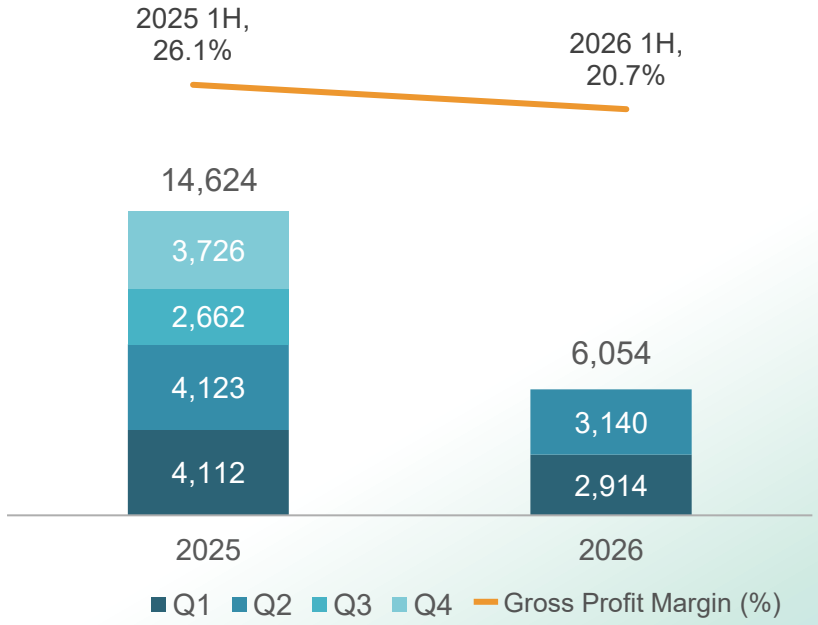
(NT$ Mn)



Gross Profit Margin (%)

- Q226 → 20.6%
- 1H26 → 20.7%

(NT$ Mn)



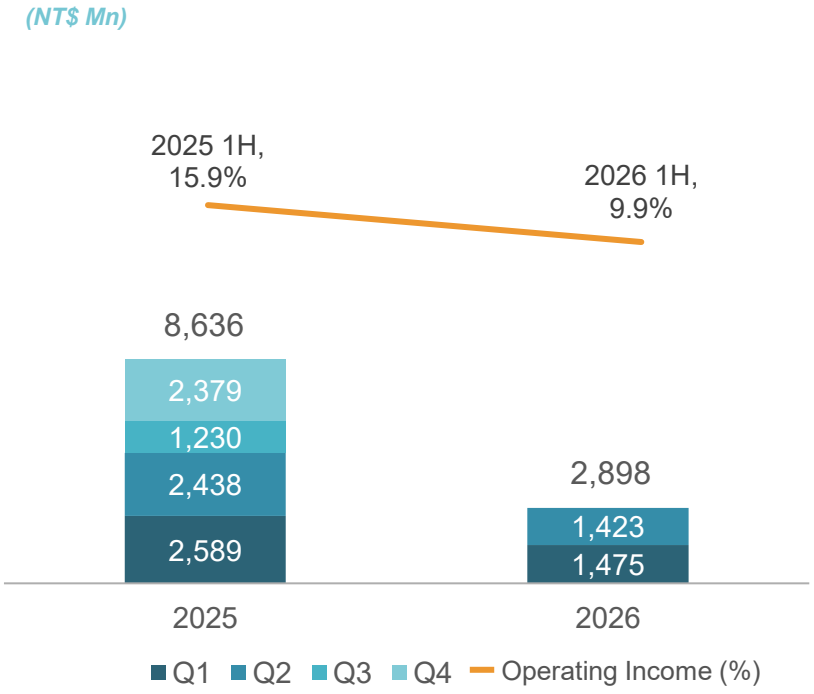
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Executive Comments

➢ Financial Highlights

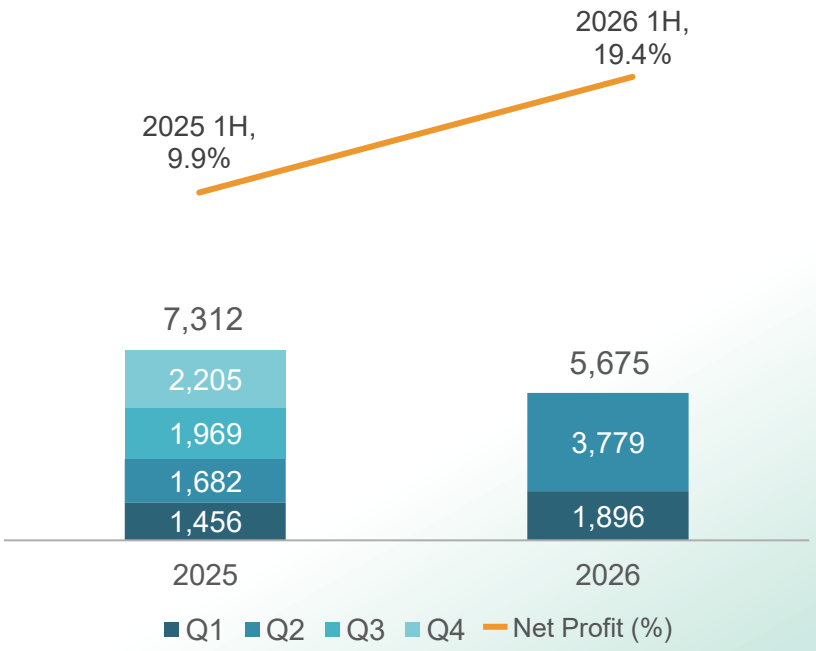
Operating Income (%)

- Q226 → 9.4%
- 1H26 → 9.9%



Net Profit (%)

- Q226 → 24.8%
- 1H26 → 19.4%



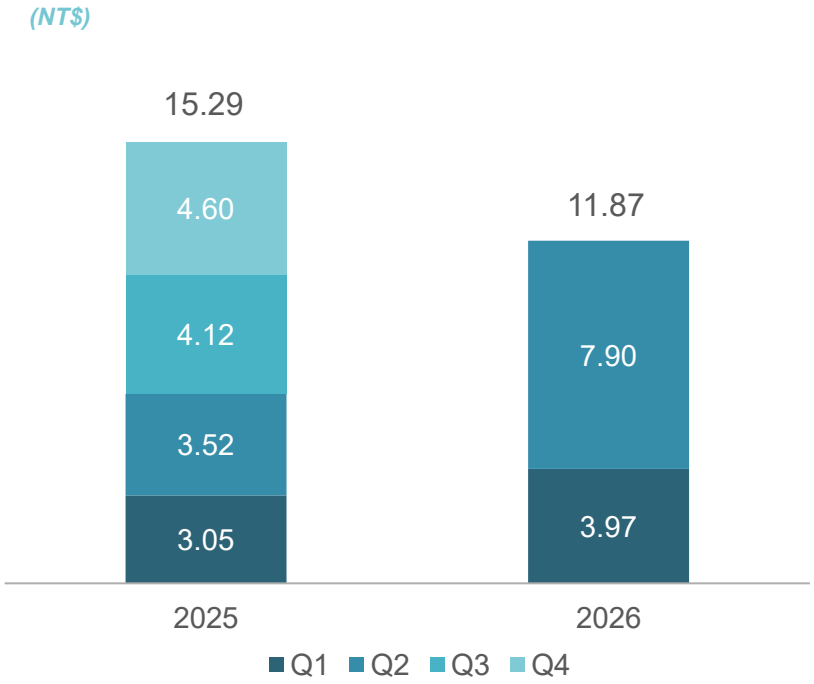
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Executive Comments

➢ Financial Highlights

EPS

- Q226 → NT$7.90
- 1H26 → NT$11.87



Prepayment

- NT$22.2 billion (US$0.66 billion)[1]

Note:
1. FX Rate: NTD:USD = 31.85, including guarantee

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Executive Comments

➢ Industry & Overview

■ Improved outlook as AI demand broadens while recovery remains gradual and uneven

- ✓ **AI demand structurally robust –** Leading hyperscalers continue to raise their AI-related capex outlooks, supporting visibility into strong demand cycle over the medium term. Rising compute and memory requirements, particularly from agentic AI and greater cloud-edge orchestration, are key drivers of this growth.
- ✓ **Recovery is broadening but remains gradual and uneven** – Customer inventory levels are returning to healthier levels, and order visibility is improving across wider range of end markets and applications. AI demand is also broadening beyond advanced nodes and improving conditions in selected mature nodes such as industrial and power, as well as extending to emerging applications (e.g. AI wearables, next-gen communications).
- ✓ **Global supply chain restructuring is reshaping priorities** – Customers are placing greater emphasis on supply certainty, regional production and operational resilience as geopolitical uncertainty continues to reshapes supply chains. Procurement criteria are broadening beyond price to include supply stability, localized and low-carbon manufacturing capabilities, product traceability, renewable energy availability, and deeper long-term collaboration.
- ✓ **Technology roadmaps are tightening advanced wafer supply**– Continued investments in AI, new packaging technologies and advanced process migration are increasing wafer intensity and qualification requirements. Supply-demand conditions remain tight across selected high-specification products, supported by strong demand and limited number of suppliers capable of producing qualified advanced wafers.

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Executive Comments

➢ Industry & Overview

■ GWC well-positioned to benefit as AI-led growth broadens across end markets

- ✓ **Improving utilization supported by stronger operating momentum –** Beyond strong demand for AI and advanced nodes, demand in mature nodes such as industrial and power management has continued to improve. Existing 12-inch wafer lines remain fully utilized, excluding newly added capacity still in the ramping stage. 8-inch wafer lines maintained high utilization with recovery extending gradually to 6-inch wafer lines.
- ✓ **Expansions beginning to bear fruit –** GWC has continued to invest in its global capacity expansion strategy in recent years. As new capacity is progressively completed and qualified, the Company is increasingly focused on customer qualification, production ramp-up and operational optimization. Combined with supportive industry fundamentals, these investments enable GWC to capitalize on growth opportunities and further unlock the value of its newer and expanded manufacturing sites.
- ✓ **Comprehensive global manufacturing footprint –** GWC's diversified production network is aligned with customers' regional expansion plans, strengthening localized supply capabilities and enabling closer, more responsive service across key markets. GWC will continue to flexibly allocate capacity according to customer demand and qualification progress, while enhancing supply stability and operational efficiency through long-term partnerships, including the recently announced strategic collaboration with Micron.
- ✓ **High-value portfolio expansion progressing –** Strong demand visibility into advanced and specialty products such as SOI, GaN, 12-inch SiC and square wafers. Most of GWC's newer sites are catered towards producing higher technology silicon wafer products, positioning the Company for future high-value opportunities.

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Semiconductor Application Trends Indicate Structural Support Beyond Cyclical Recovery

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Compute & AI Infrastructure

Structurally Robust

- Still early innings of a multi-year AI proliferation, supported by hyperscaler capital expenditure plans that have continued to be revised upwards during this year.
- Leading players continue to invest in advanced-node capacity for future inference and cloud-edge demands, reinforcing sustained long-term demand for leading-edge silicon wafers.
- Agentic AI is broadening data center architectures beyond AI accelerators to include greater CPU content, increasing silicon requirements.



Memory Market

Solid Fundamentals

- Despite ongoing capacity expansion, supply constraints are expected to persist over the next few years, supported by favorable industry conditions.
- Customers are securing supply through long term agreements, providing stronger visibility into near to medium term wafer demand.
- Rising HBM adoption and increasing memory complexity are driving greater wafer requirements, supporting sustained demand for silicon wafers.



Smartphone & PC

Stabilizing Demand

- AI-enabled and premium devices continue to increase semiconductor content per device, supporting demand for higher-value logic, memory, and RF components.
- An aging installed base and the rollout of AI-capable smartphones and PCs are expected to support a multi-year device refresh cycle, reinforcing long-term semiconductor demand.

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Semiconductor Application Trends Indicate Structural Support Beyond Cyclical Recovery (cont'd)

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Automotive & Industrial

Gradual Recovery with Rising Silicon Content

- Demand conditions across power and industrial applications are gradually improving, while automotive semiconductor demand remains mixed as inventories normalize. Rising semiconductor content per vehicle continues to support medium-term demand.
- Growth in ADAS, software-defined vehicles and increasingly intelligent vehicle architectures is driving higher demand for logic, sensors, power and connectivity semiconductors.
- Continued investment in robotics and physical AI represents an additional long-term demand driver for logic, memory, sensors and power devices, supporting broader silicon wafer demand.

Advanced Packaging

Solid Fundamentals

- Packaging technologies, including CoWoS, CoPoS, Wafer-on-Wafer and HBM stacking, are becoming increasingly critical to AI system performance as chipmakers integrate more dies and components within complex architectures.
- These technologies require multiple wafer layers, tighter specifications and more complex manufacturing process, while lower yields can further increase wafer requirements per system, supporting demand for advanced and specialty wafers.

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Company Overview

AI Infrastructure Investment is Driving Structural Growth In Wafer Demand

Rising AI Capex

- AI demand remained robust in 2Q 2026, with continued enterprise adoption and broader AI use cases continuing to support capital investment.
- Consensus estimates for cumulative hyperscaler AI capex increased by approximately US$1.3 trillion (+58%) for 2026–2029 versus December 2025, reinforcing sustained investment in advanced semiconductor manufacturing.

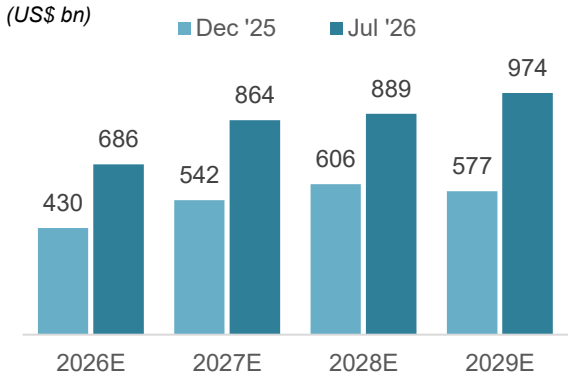
Semiconductor Expansion

- Leading semiconductor manufacturers continue expanding advanced logic and HBM manufacturing capacity, reinforcing long-term wafer demand as new production lines progress toward production.
- Capacity expansion across the US, Japan, Korea, and Europe reflects manufacturers' localization strategies and reinforces regional semiconductor manufacturing ecosystems.

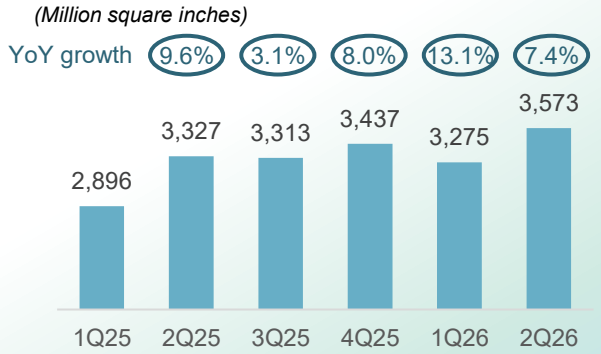
Sustained Wafer Demand for GWC

- AI-driven capacity expansion continues to translate into sustained demand across GWC's silicon wafer portfolio.
- Strong utilization across GWC's production network reflects healthy customer demand as new capacity ramps.
- Long-term customer engagement continues to support visibility into future wafer demand.

Top US Hyperscalers' CAPEX Estimates by Date[1]



Worldwide Silicon Wafer Shipments



Source: Company filings, SEMI Silicon Wafer Shipment Statistics (Jul 2026), FactSet (as of 07/18/2026)
Notes: 1. Represents figures for Amazon, Meta, Microsoft, Alphabet and Oracle

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New Applications Are Broadening Demand for Silicon, SOI and Compound-Semiconductor Wafers

AI Wearables & Edge

- AI inference is expanding to edge devices, increasing demand for low-power sensing, connectivity, power-management technologies, and high-performance edge computing chips.
- Growing adoption of SOI, GaN, and SiC, advanced epitaxial wafers, and polished wafers is supporting sensing and MicroLED display applications (e.g., AR glasses).

AI Servers & Packaging

- Agentic AI is driving broader demand across CPUs, ASICs, GPUs, HBM, and power semiconductors, resulting in higher wafer intensity.
- Higher AI power density accelerates adoption of SiC thermal management, GaN power technologies and square panels for advanced packaging.
- GaN power device market projected ~$3bn by 2030, ~42% CAGR from 2024.

Next-Gen Communications

- AI clusters increasingly rely on high-speed optical interconnects, driving structural demand for silicon photonics.
- Demand for silicon photonics substrates (Photonics-SOI) is growing rapidly, with a CAGR of over 35%.

Electrification & Automation

- Electrification, robotics and industrial automation are accelerating adoption of SiC, GaN power semiconductors and Power-SOI.
- Higher-voltage, higher-efficiency systems require next-generation compound semiconductor materials.
- SiC power device market projected ~$110bn by 2031, ~20% CAGR from 2025.

Expanding AI Applications Drive Demand for Advanced-Node, Specialty, and Mature-Node Wafers

Mix Improvement
Accelerating adoption of SOI, compound-semiconductor wafers and square wafers supports a higher-value product mix

Broader Volume Growth
Growing demand for analog, power and industrial semiconductors supports stronger demand for 12-inch, 8-inch and 6-inch wafers

Long Term Growth
Broader end-market exposure supports more diversified and sustainable long-term growth

Source: Yole Group (Oct 2025 and Jun 2026); Kaiso Research (Jun 2026)

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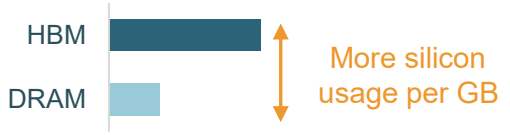
GWC's Local Manufacturing Footprint is Aligned with Customer Capacity Expansion

- GWC's global manufacturing footprint is increasingly aligned with customer localization requirements, enabling closer customer collaboration and more resilient regional supply, and greater support for customers' traceability and sustainability requirements.
- Localized manufacturing is strengthening strategic customer relationships, as demonstrated by its recently announced long-term collaboration with Micron in July 2026 to support US wafer supply chain localization.
- GWC's expansion investments are beginning to bear fruit, with the focus shifting from fab construction to customer qualification and production ramp-up as new capacity begins contributing to revenue and earnings.

	Site	Status	Ecosystem Capacity Highlights
On-going Expansion	Sherman, Texas, US	■ Successfully completed qualification with multiple customers. ■ Ongoing process optimization.	>$600B of announced U.S. expansion by leading semiconductor manufacturers supports localized manufacturing demand
	St. Peters, Missouri, US	■ Customer sampling activities are ongoing. ■ RF-SOI and silicon photonics products have entered small-volume production.	>$10B of announced investment by leading semiconductor manufacturers reinforces long-term demand for specialty wafers, including SOI
	Novara, Italy	■ Initial customer qualifications are progressing smoothly. ■ Capacity utilization will be steadily ramped up in line with customer qualification progress and market demand.	>$10B of announced investment by leading semiconductor manufacturers supports Europe's power semiconductor ecosystem
Recent Completion	Utsunomiya, Japan	■ Capacity expansion has been successfully completed, with all additional capacity fully in place. ■ Overall capacity utilization remains at a high level. ■ Operational and financial performance continue to improve.	>$30B of announced investment by leading semiconductor manufacturers supports advanced semiconductor manufacturing in Japan

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Semiconductor Technology Roadmaps Are Increasing Silicon Wafer Content and Value

Select areas of technology transitions	Example
Advanced packaging architectures are increasing wafer consumption per system ■ Wafer-on-wafer, CoWoS, HBM stacking and silicon interposers require significantly greater silicon area and wafer consumption per end system.	**Representative AI accelerator architecture:** 2.5D and 3D multi-die packaging require greater silicon area per device than traditional monolithic designs, increasing overall silicon wafer consumption
HBM structurally increases wafer intensity ■ Larger die sizes and TSV-enabled 3D stacking require more silicon per unit of memory capacity vs. conventional DRAM.	
Advanced-node scaling increases wafer complexity and value ■ The migration from FinFET to Gate-All-Around (GAA) and Backside Power Delivery (BSPDN) requires tighter silicon wafer specifications and manufacturing tolerances. ■ Growing demand for wafer bonding is creating new requirements for specialized silicon wafer parameters.	As demand for new metrology and manufacturing equipment grows, academia collaboration, supplier co-development, and in-house R&D advance in parallel.
Advanced-node migration is lifting wafer value ■ Advanced-node manufacturing requires silicon wafers with higher purity, greater flatness, tighter defect control, and other specialized specifications, increasing the value of high-specification wafers.	Silicon wafer products required for advanced-node manufacturing command significantly higher value than those used in mature-node manufacturing.

GWC's differentiated technology portfolio is aligned with evolving semiconductor technology roadmaps

12-inch SOI
- Driven by continued growth in silicon photonics demand, SOI production continues to ramp up, with demand exceeding supply.

GaN
- Capacity remains fully utilized with expansion progressing (~30% completed, ~20% underway).

SiC
- 12-inch SiC qualification is progressing with multiple customers, supporting future commercialization.

Square wafers
- Qualification activities with multiple customers are progressing smoothly.

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03

Financial Performance

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Financial Highlight : Q226 vs. Q126 vs. Q225

(NT$ Mn, except EPS)	Q226	Q126	Q225	QoQ	YoY
Revenue	15,214	13,985	16,008	8.8%	-5.0%
Gross Profit %	20.6%	20.8%	25.8%	-0.2p.p.	-5.2p.p.
Operating Income	1,423	1,475	2,438	-3.6%	-41.6%
Operating Income %	9.4%	10.5%	15.2%	-1.1p.p.	-5.8p.p.
Net Profit	3,779	1,896	1,682	99.3%	124.7%
Net Profit %	24.8%	13.6%	10.5%	11.2p.p.	14.3p.p.
EPS[1]	NT$7.90	NT$3.97	NT$3.52	NT$3.93	NT$4.38
EBITDA[2]	6,969	4,060	4,472	71.6%	55.9%
EBITDA %	45.8%	29.0%	27.9%	16.8p.p.	17.9p.p.
EBIT[3]	4,556	1,855	2,027	145.5%	124.8%
ROE[4] (annualized)	15.9%	8.1%	7.6%	7.8p.p.	8.3p.p.
ROA[5] (annualized)	8.15%	4.17%	3.40%	3.9p.p.	4.7p.p.
Capex[6]	2,202	3,460	7,537	-	-
Depreciation	2,408	2,199	2,440	-	-

Note: 1. EPS = Net Profit Attributable To The Shareholders of The Company / Weighted-average Number of Ordinary Shares Outstanding During The Period
2. EBITDA = Net Profit + Tax + Interests + Depreciation + Amortization
3. EBIT = Net Profit + Tax + interests
4. ROE = Net Profit / Average Shareholders Equity
5. ROA = (Net Profit + Interest(1- Effective Tax Rate)) / Average Asset*
6. Capex = Ending Acquisition of property, plant and equipment, and prepayments of equipment - Beginning Acquisition of property, plant and equipment, and prepayments of equipment

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Financial Highlight : 1H26 vs. 1H25

(NT$ Mn, except EPS)	1H26	1H25	YoY
Revenue	29,199	31,602	-7.6%
Gross Profit %	20.7%	26.1%	-5.4p.p.
Operating Income	2,898	5,027	-42.4%
Operating Income %	9.9%	15.9%	-6.0p.p.
Net Profit	5,675	3,138	80.9%
Net Profit %	19.4%	9.9%	9.5p.p.
EPS[1]	NT$11.87	NT$6.56	NT$5.31
EBITDA[2]	11,029	8,505	29.7%
EBITDA %	37.8%	26.9%	10.9p.p.
EBIT[3]	6,411	3,804	68.5%
ROE[4] (annualized)	11.9%	7.1%	4.8p.p.
ROA[5] (annualized)	6.05%	3.2%	2.9p.p.
Capex[6]	5,662	19,094	-
Depreciation	4,607	4,689	-

Note: 1. EPS = Net Profit Attributable To The Shareholders of The Company / Weighted-average Number of Ordinary Shares Outstanding During The Period
2. EBITDA = Net Profit + Tax + Interests + Depreciation + Amortization
3. EBIT = Net Profit + Tax + interests
4. ROE = Net Profit / Average Shareholders Equity
5. ROA = (Net Profit + Interest(1- Effective Tax Rate)) / Average Asset*
6. Capex = Ending Acquisition of property, plant and equipment, and prepayments of equipment - Beginning Acquisition of property, plant and equipment, and prepayments of equipment

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Income Statement

(NT$ Mn)	2025	Q126	Q226	1H26	1H26 (simulated)[1]
Revenue	**60,598**	**13,985**	**15,214**	**29,199**	**27,502**
YoY Growth (%)	*-3.2%*	*-3.6%*	*8.8%[2]*	*-7.6%*	-
Gross Profit	**14,624**	**2,914**	**3,140**	**6,054**	**8,918**
Gross Profit Margin (%)	*24.1%*	*20.8%*	*20.6%[3]*	*20.7%[4]*	*32.4%*
EBITDA	**17,340**	**4,060**	**6,969**	**11,029**	**10,433**
EBITDA Margin (%)	*28.6%*	*29.0%*	*45.8%*	*37.8%*	*37.9%*
Operating Income	**8,636**	**1,475**	**1,423**	**2,898**	**6,214**
Operating Profit Margin (%)	*14.3%*	*10.5%*	*9.4%*	*9.9%*	*22.6%*
Profit before Tax	**9,516**	**2,347**	**4,585[5]**	**6,932**	**6,825**
Profit before Tax Margin (%)	*15.7%*	*16.8%*	*30.1%*	*23.7%*	*24.8%*
Net Profit	**7,312**	**1,896**	**3,779[5]**	**5,675**	**5,384**
Net Profit Margin (%)	*12.1%*	*13.6%*	*24.8%*	*19.4%*	*19.6%*
EPS (NT$)	**15.29**	**3.97**	**7.90[5]**	**11.87**	**11.26**

Note: 1. Simulated figures exclude impacts from major expansions in the U.S., Italy, and Japan, as well as mark-to-market changes on Siltronic shares
2. Quarter-over-quarter (QoQ) for 2Q26 revenue growth
3. Q226 Gross Profit Margin remained broadly stable QoQ despite revenue growth, mainly reflecting higher depreciation, compensation accruals and cost pressures from freight, and energy expenses.
4. 1H26 Gross Profit Margin declined YoY, mainly reflecting higher depreciation and other expansion-related costs.
5. Q226 Profit before Tax, Net Profit, and EPS increased QoQ, mainly from mark-to-market gains on Siltronic shares

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Balance Sheet

(NT$ Mn)	2024	2025	Q126	Q226
Assets				
Cash and cash equivalents	38,929	19,484	24,128	23,776
Account receivable	10,265	10,113	10,138	10,548
Inventories	11,238	10,399	11,000	12,015[3]
Property, plant and equipment	119,074	107,241	108,861	107,864
Other assets	45,074	71,105	56,910	65,017
Total assets	**224,581**	**218,343**	**211,037**	**219,220**
Liabilities				
Short-term loan[1]	28,797	31,010	33,887	38,282[4]
Account payable	5,371	4,161	3,867	4,697
Long term loan[2]	37,678	43,244	29,221	33,188[4]
Other liabilities	61,706	46,632	50,683	46,333
Total liabilities	**133,553**	**125,048**	**117,657**	**122,500**
Shareholder equity	**91,028**	**93,295**	**93,379**	**96,720**

Cash-related other assets include:	
(*NT$ Mn*)	**Q226**
Deposits in banks held for three months or more	4,768
Restricted Cash	18,019
Note	6,338

Note: 1. The balance of short-term loans comprises short-term borrowings, commercial paper payable, and the current portions of long-term borrowings, corporate bonds payable, and convertible bonds payable
2. The balance of long-term loans includes long-term borrowings, corporate bonds payable, and exchangeable bonds payable
3. Q226 Inventories increased QoQ, mainly due to inventory build-up in preparation for anticipated demand in H2.
4. Q226 Short-term and long-term loans increased QoQ, mainly reflecting global liquidity management and funding needs for operations and expansion.

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04

ESG

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Sustainable Environment – SBTi

- GlobalWafers' near- and long-term emissions reduction targets were validated by the SBTi in May 2026, advancing its journey toward net zero by 2050. The Company is accelerating decarbonization through operational improvements, renewable energy expansion, and supplier engagement to support lower-carbon and more traceable supply chains.

Science-Based Emissions Targets & Decarbonization Strategy



Net-zero emissions across the entire value chain **by 2050**

Scope	Near-term Target (2035)	Long-term Target (2050)
Scope 1 & 2 (2022 base year)	63% reduction	90% reduction
Scope 3 (2024 base year)	**37.5% reduction** *(Categories 1–3)*	**90% reduction** *(all categories)*



Process & Equipment Optimization



Expand Renewable Energy Adoption



Supplier Carbon Footprint Assessments



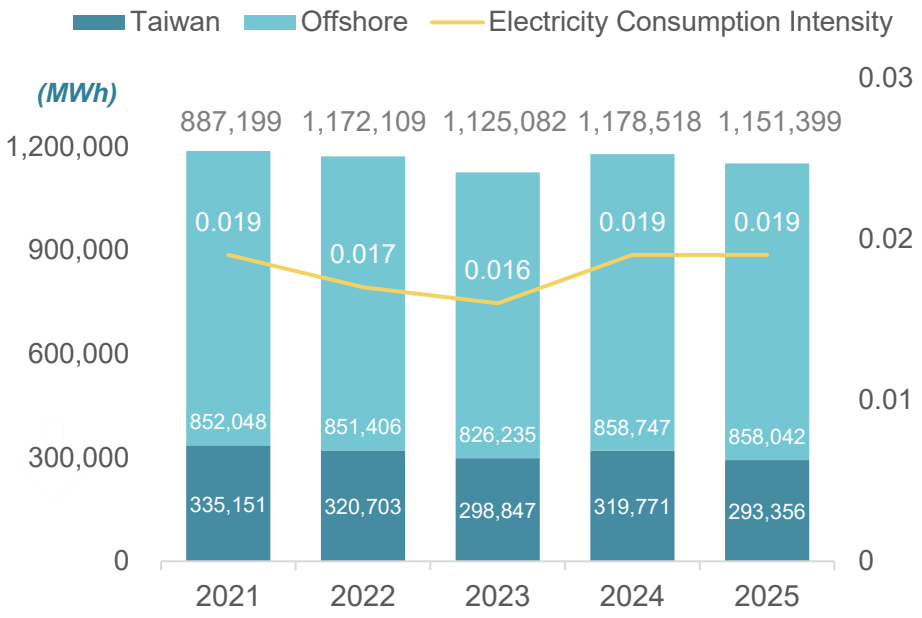
SBTi Engagement with Key Suppliers

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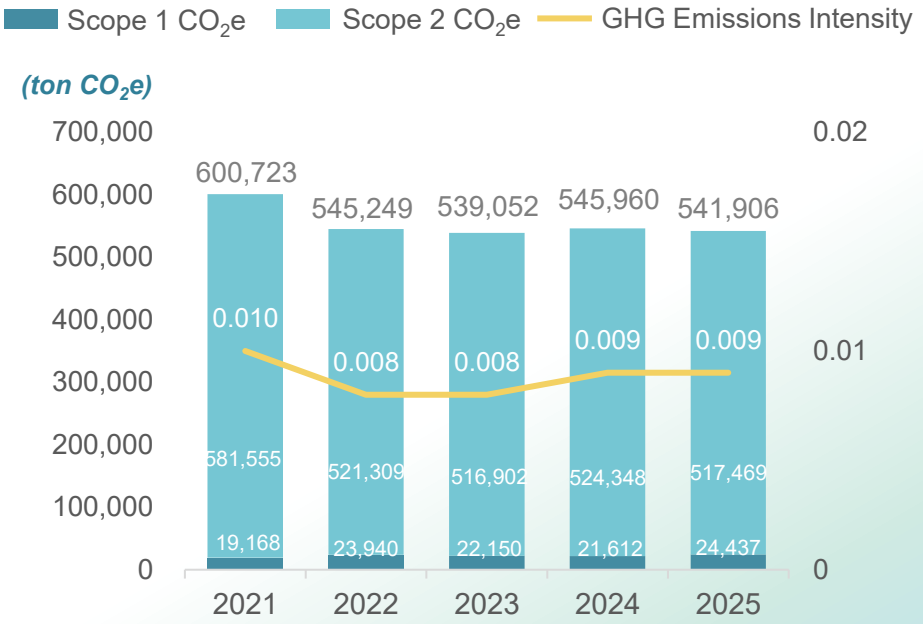
Sustainable Environment – GHG & Electricity

- **Electricity Consumption:** Total electricity consumption remained broadly stable at 1.15 million MWh in 2025, while electricity consumption intensity was maintained at 0.019, demonstrating the Company's continued focus on operational efficiency amid global business expansion.
- **GHG Emissions:** Scope 1 and Scope 2 GHG emissions totaled approximately 542 thousand tons CO_2e in 2025, with emissions intensity remaining stable at 0.009, reflecting ongoing progress in emissions management and the Company's long-term decarbonization strategy.

Electricity Consumption & Intensity[1], 2021-2025



GHG Emissions & Intensity[2] (Scope 1&2), 2021-2025



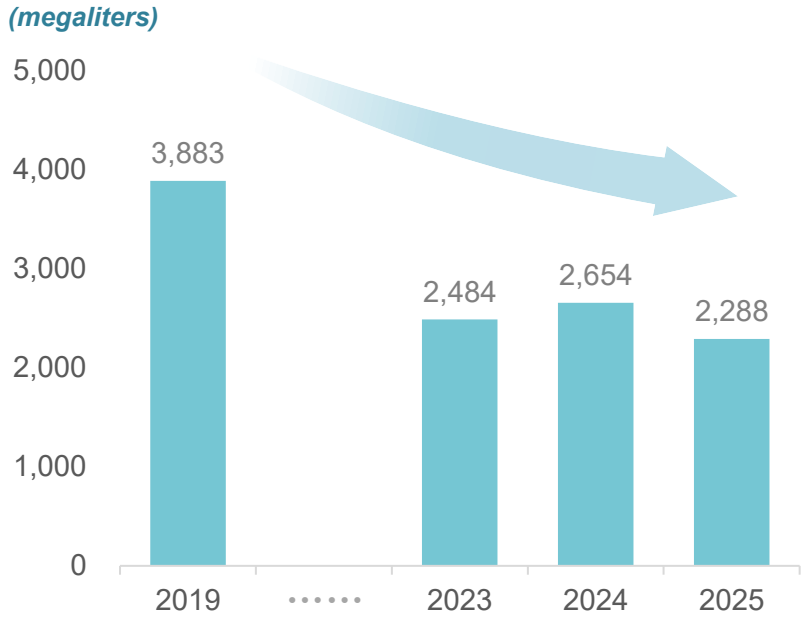
Note: 1. Electricity Consumption Intensity = MWh / Consolidated revenues (NTD thousands).
2. GHG Emissions Intensity = ton CO_2e / Consolidated revenues (NTD thousands).

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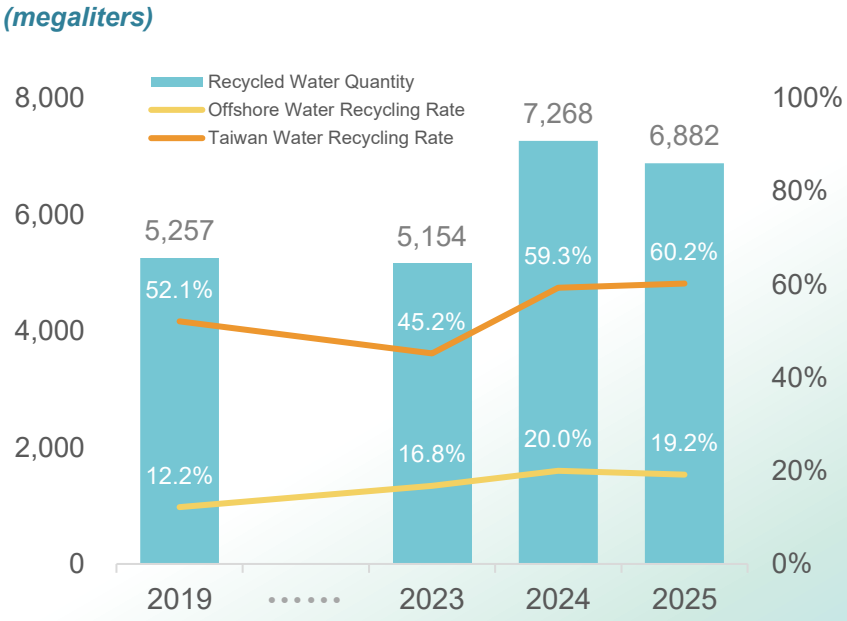
Sustainable Environment – Water

- **Water Consumption:** Total water consumption decreased to 2,288 megaliters in 2025, down 13.8% year-on-year and approximately 41% compared with 2019, reflecting the Company’ s continued efforts in water conservation and process efficiency.
- **Water Recycling:** Recycled water volume remained at a high level of 6,882 megaliters in 2025. Taiwan’ s water recycling rate continued its upward trend in recent years, reaching 60.2% in 2025—the highest level in recent years—reflecting the Company’ s continued efforts to enhance water reuse and advance circular economy practices.

Water Consumption Quantity, 2019-2025



Water Recycle, 2019-2025

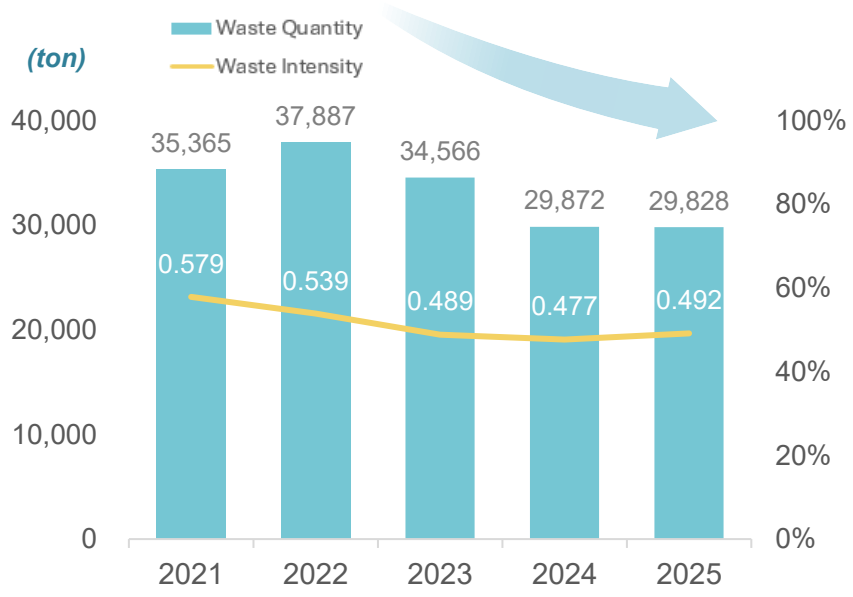


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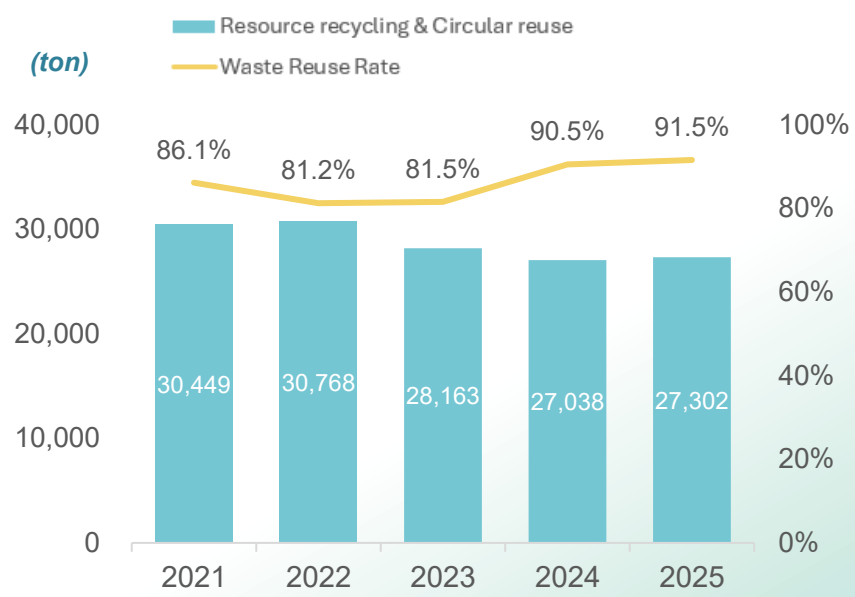
Sustainable Environment – Waste

- **Waste Generation:** Total waste generation remained broadly stable at approximately 29.9 thousand tons in 2025, while waste intensity was maintained below the 2021 level, reflecting the Company’ s continued focus on waste reduction and operational efficiency.
- **Waste Reuse:** The waste reuse rate increased for the third consecutive year to 91.5% in 2025, the highest level in recent years, demonstrating continued progress in resource recycling, waste reuse, and the Company’ s broader circular economy practices.

Waste Quantity & Waste Intensity[1], 2021-2025



Waste Reuse, 2021-2025



Note: 1. Waste Intensity = ton / Consolidated revenues (NTD thousands).

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Biodiversity in Action: Protecting Marine and Urban Ecosystems

- GlobalWafers integrates biodiversity considerations into its environmental management and advances locally relevant actions across marine and urban ecosystems. These initiatives reflect the Company's ongoing efforts to protect habitats, strengthen ecological resilience, and support long-term biodiversity conservation.

7,011 kg
of marine and coastal waste recovered

3 Urban Green Spaces

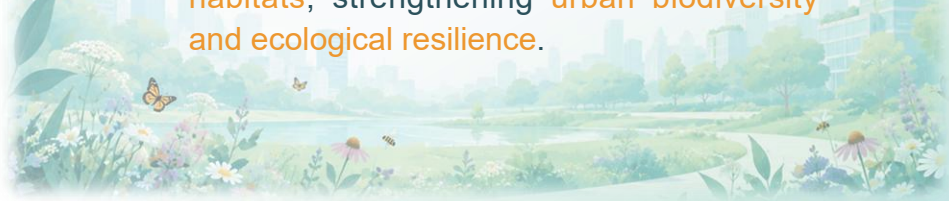
Marine Ecosystem Protection

- Through a three-year partnership with Ogyre, GlobalWafers' Italian subsidiary supports local fishing communities in removing marine debris across Italy, Brazil, Indonesia, and Senegal.
- The initiative helps reduce pressure on marine habitats while supporting healthier and more resilient coastal ecosystems.



Urban Biodiversity Initiatives

- Since January 2026, GlobalWafers' Italian subsidiary SPA has supported the management of three urban green spaces through the municipality-led "Novara City in Green" initiative.
- The project helps create pollinator-friendly habitats, strengthening urban biodiversity and ecological resilience.



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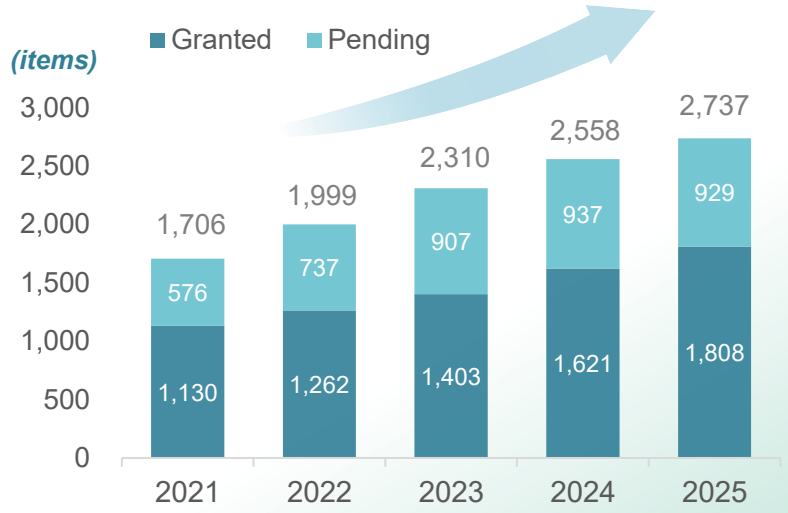
ESG Highlights: Corporate Governance

- GlobalWafers continues to earn external recognition for its strong corporate governance practices. The Company ranked in the Top 5% of the TPEx Corporate Governance Evaluation for the 8th consecutive year and remained a constituent of the FTSE4Good Index Series for the 4th consecutive year.
- GlobalWafers also continues to strengthen its innovation and intellectual property capabilities. The Group held 2,737 active patents in 2025, covering 1st- to 3rd-generation semiconductor technologies, and ranked among Taiwan's Top 100 domestic patent applicants for the 5th consecutive year, while achieving TIPS AA Certification for the 6th consecutive year.

Corporate Governance Achievements

- Top 5% in TPEx Governance (8th year)
- FTSE4Good Index Series (4th year)
- Top 100 domestic patent applicant (5th year)
- Achieved TIPS AA Certification (6th year)
- Hsinchu Science Park R&D Accomplishment Award

Active Patents (Group Total, 2021–2025)



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Global Community Engagement in 2026

- Across Asia, Europe, and the Americas, GlobalWafers supports local communities through charitable giving, employee volunteering, STEM education, and community outreach, creating positive social impact in the regions where it operates. Together, these initiatives strengthen community connections, support local needs, and contribute to more inclusive and resilient communities.

Community Initiatives in 2026 Across Our Global Footprint

Americas
Inspiring Future Talent




- Supported Science, Technology, Engineering, and Mathematics (STEM) career development.
- Built a network connecting women professionals across industries.

Asia
Community in Action





- Volunteered at a children's welfare center.
- Co-organized a blood donation drive.

Europe
Care & Giving




- Supported a children's cancer foundation.
- Donated toys to children in need.

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Q&A